

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1. (currently amended): A semiconductor device comprising:

an organic insulating film having an opening,

wherein said organic insulating film has an insulated modified portion in a side of said opening, and

said modified portion includes nitrogen atoms and carbon atoms forming carbon-nitrogen bonds.

Claim 2. (previously presented): The semiconductor device according to claim 1,

wherein said modified portion further comprises fluorine atoms, and

a concentration of said fluorine atoms in said modified portion is lower than a concentration of said nitrogen atoms.

Claim 3. (original): The semiconductor device according to claim 2, further comprising:

a metal conductor whose main component is copper, formed in said opening.

Claim 4. (previously presented): The semiconductor device according to claim 3,

wherein said metal conductor is in direct contact with said modified portion.

Claim 5-18 (canceled).

Claim 19. (previously presented): The semiconductor device according to claim 4,
wherein the metal conductor comprises a barrier film whose main component is tantalum.

Claim 20. (previously presented): The semiconductor device according to claim 19,
wherein the barrier film is in direct contact with the modified portion.